

A8aL Flying Probe Test System Dual Shuttle

Automated Test for Rigid and Flexible Boards

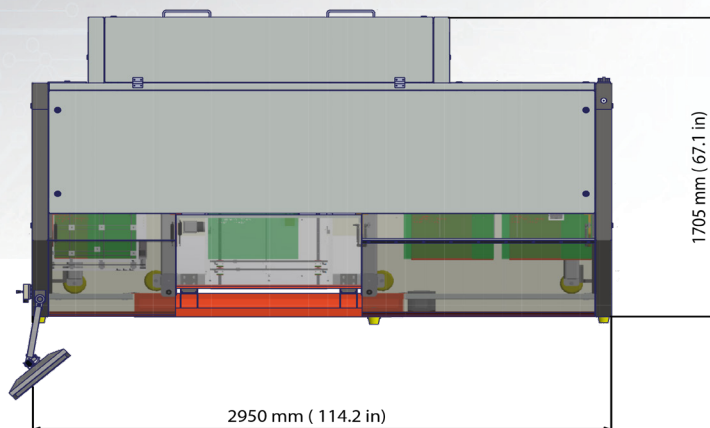


- ▲ 8 Test Heads
- ▲ Fully Automatic “Lights-out” operation
- ▲ Dual Shuttle System
- ▲ Tension Option for thin core and flexible panels
- ▲ Fast 300 mA Kelvin Testing

A8aL Technical Specifications

Dual Shuttle

Flying Probe Test System



Plan View

Mechanics

Fully automated test system for medium batch sizes in lights-out operation.
Basic unit with 8 test probes (4 top, 4 bottom)

Board Handling

Automation mode:	
Max. board size (X x Y)	480 mm x 420 mm / 18.9" x 16.5"
Test area (X x Y)	480 mm x 420 mm / 18.9" x 16.5"
Manual mode:	
Max. board size (X x Y)	610 mm x 535 mm / 24.0" x 21.0"
Test area (X x Y)	610 mm x 510 mm / 24.0" x 20.0"
Min. board size (X x Y)	
Board thickness	50 mm x 40 mm / 2.0" x 1.6" up to 5 mm, max. 2 kg
Product exchange time	0 s with dual shuttle mode, for test area max. 300 mm x 330 mm
Loader capacity	390 mm 240 boards / 1.6 mm thickness
Smallest pad	
Smallest pitch	50 µm / 2.0 mil 100 µm / 4.0 mil
Resolution measurement system	± 0.1 µm / ± 0.004 mil
Repeatable accuracy	± 4 µm / ± 0.16 mil
Soft touch probes	
*Micro needle probes	5 g to 10 g 0.3 g to 2.5 g

Electronics

Continuity test	1 Ω to 10 kΩ (2-wire)
Isolation test	up to 25 MΩ (FM), up to 100 GΩ (ohmic) MicroShort Detection®
Test voltage	100 mV to 1000 V

Camera System

4 color cameras for fast optical scanning of top and bottom side.
Resolution 9 µm/ pixel

Options

- 4-wire measurement with max. 300 mA test current
0 Ω to 1 kΩ ± 2 %, min. ± 25 µΩ
with Kelvin probes 0.3 g to 2.5 g
Smallest pad 80 µm / 3.2 mil*
Smallest pitch 120 µm / 4.8 mil*
* special setup
- Embedded components test

R	0 Ω to 1 MΩ	± 1 %, min. ± 0.5 Ω
	1 MΩ to 200 MΩ	± 3 %
C	0 F to 100 µF	± 2 %, min. ± 30 fF
L	0 H to 10 mH	± 5 %, min. ± 0.25 µH
Diode / Varistor		(on inquiry)
	U_{F1}, U_{R1}, U_{BR1}	0 V to 12.5 V
- Structural test of integrated circuits:
opens/shorts test on CMOS devices with ESD diodes
- LaTest® open detection
- Label printer with barcode support
- Pen marker
- Retest of fault files from external grid test systems on inquiry
- Repair software with barcode support
- Tensioning modules for flexible board thickness 0,05 mm to 1.0 mm



Data input format	IPC-D-356A
Network connection	Ethernet, TCP / IP
Power supply	3 x 400 V, 50 Hz (3 x 208 V, 60 Hz), 1500 VA
Compressed air	8 bar / 115 psi, filtered
Temperature	18 °C to 27 °C
Relative humidity	40 % to 60 %
Machine weight	1900 kg

All information subject to change without notice!
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